Atty. Docket No. OF03P212/US

RECEIVED
CENTRAL FAX CENTER

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

JUN 2 2 2005

IN RE APPLICATION OF:

Jac Suk LEE et al.

: GROUP ART UNIT: 2823

M.K TO ENTER

APPLICATION NO: 10/733,884

FILED: DECEMBER 3, 2003

: EXAMINER: DANG, Trung

T. Dang.

FOR: METHOD OF MANUFACTURING A SEMICONDUCTOR DEVICE

I hereby certify that this document is being facsimile transmined to the USPTO, <u>Mail Stap AF</u>, or deposited with the United States Postal Service as first class mail in an envelope addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on <u>June 22, 2005</u>.

By: Service Heaton

AMENDMENT AND REQUEST FOR RECONSIDERATION UNDER 35 U.S.C. 132 AND 37 C.F.R. 1.111

Mail Stop AF COMMISSIONER FOR PATENTS P.O. BOX 1450 ALEXANDRIA, VA 22313-1450

SIR:

Responsive to the Office Action dated March 25, 2005, Applicant elects, with traverse, Group I, Claims I and 3-9, drawn to a method of manufacturing a semiconductor device, and (also with traverse) Group A, Claims I and 3-9, directed to a method that comprises etching parts of the insulating layer where a plurality of via holes will be formed to a certain thickness so as not to expose the first conductive line, and respectfully requests (i) entry of the following amendments and (ii) consideration of the following remarks.